

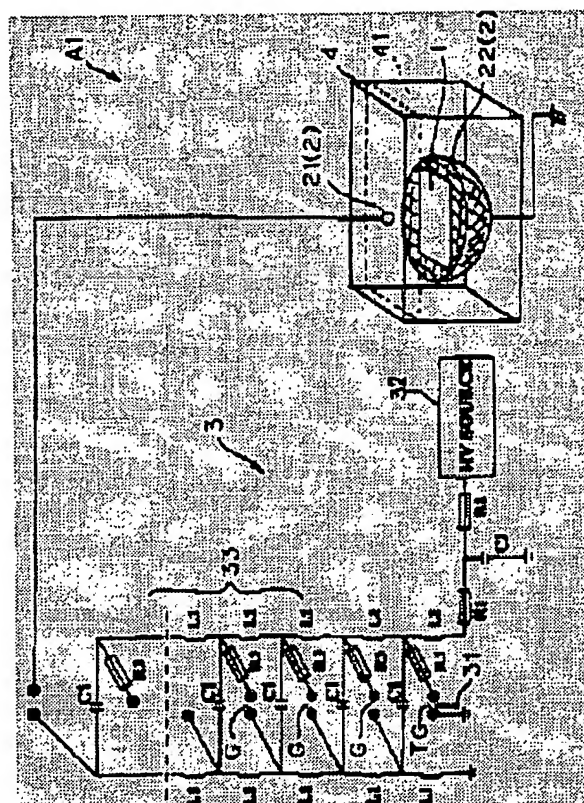
# METHOD AND APPARATUS FOR SEPARATION OF JUNCTION BODY

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## Abstract of JP2000037622

**PROBLEM TO BE SOLVED:** To separate a raw material from a suitable area almost uniformly in a short time by forming a pulse discharge so as to spread in the suitable area on a junction body when the junction body is arranged between a pair of electrodes, a high tension pulse is impressed between a pair of the electrodes to generate the pulse discharge, and the raw materials are separated from the junction body. **SOLUTION:** A separation apparatus A1 of a junction body is equipped with a couple of electrodes 2, a high tension pulse generating part 3, and a treating tank 4 wherein a liquid medium 41 in which a couple of the electrodes 2 are dipped is filled. In the case where raw materials of a conductive member, an electronic circuit element or the like are separated from a printed substrate 1, the printed substrate 1 is arranged between a couple of electrodes 2 to generate a high-tension pulse discharge by a high-tension pulse generation part 3 between a couple of the electrodes 2, and the raw materials are separated from the printed substrate 1 by an impulse wave and a heat to be generated following the pulse discharge. In this case, a rise time of the high-tension pulse to be impressed between a couple of the electrodes 2 is set low to, for example, a value of 700 n sec or under, and the pulse discharge is formed so as to spread in a suitable area on the printed substrate 1.



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